

Plasma Surface Engineering

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Table of Contents

Volume 1

General Aspects

- Plasma Surface Engineering: Technological Trends and Impacts 3
A. Hauff, Hanau, FRG
- The Plasma Environment in Inorganic Thin Film Deposition Processes 15
D. M. Mattox, Albuquerque, NM, USA

Modelling of Plasma Assisted Deposition

- Mechanisms of Metal Film Oxidation in the Pressure Range 37
 10^{-10} to 1 bar O₂
E. Fromm, V. Grajewski, H. H. Uchida, Stuttgart, FRG
- Reaction Probability of Nitrogen on the Titanium Nitride Film Formation 45
by Hollow Cathode Discharge Process
Y. Matsumura, H. Uchida, Y. C. Huang, Kangawa, Japan
- Mathematical Model for Carbon Supply Rate in Plasma Carburizing 53
Y. Zhao, Z. Zhang, S. Chen, D. Wang, Dalian, P.R. China
- Coating Thickness and Composition Uniformity in Plasma Assisted PVD 61
K. S. Fancey, A. Matthews, Hull, U.K.
- Ion Carburizing with Propane-Butane and Argon-Methane 69
D. I. Trifonov, Rousse, Bulgaria
- A Model of Growth of New Phase Layers under Plasma-Surface 73
Interaction
Z. A. Iskanderova, G. R. Rakhimova, USSR

Plasma Diagnostics

- Excited States of Plasmas for Steel Surface Nitriding 83
A. Ricard, Orsay, J. Oseguera, H. Michel, M. Gantois, Nancy, France
- Spectroscopic Studies of N₂-H₂-TiCl₄ Glow Discharge used for TiN 91
Deposition
B. Kulakowska, W. Zyrnicki, N. Badowski, Wroclaw,
T. Wierzchoń, T. Karpiński, Warsaw, Poland

Characterization of Low Pressure High Frequency Plasmas by DC Probe Measurements	99
K. Franzreb, A. Fuchs, H. Oechsner, Kaiserslautern, FRG	
Study of Probe Diagnostics in Plasma Polymerization Process by Means of Computer Experiment	107
S. Novák, Ústi n/L, R. Hrach, V. Hrachová, Prague, CSSR	
Spectral Diagnostics of Glow Discharge in N ₂ , Ar and N ₂ -Ar Atmospheres	115
B. Kulakowska, W. Zyrnicki, Wroclaw, Poland	

Plasma Assisted CVD of Hard Coating

Plasma Assisted CVD of TiN on Steels and Geometric Effects	125
K.-T. Rie, St. Eisenberg, A. Gebauer, Braunschweig, FRG	
Plasma-CVD of Cemented Carbides	133
R. Tabersky, H. van den Berg, U. König, Essen, FRG	
Deposition of Titanium Nitride by RF Frequency Plasma CVD	139
H. P. Lorenz, Erlangen, FRG	
The Properties of the Titanium Nitride Deposited by	
Plasma Enhanced Chemical Vapour Deposition	147
D. H. Jang, S. B. Kim, J. S. Chun, Seoul; J. G. Kim, Incheon, Korea	
Plasma Chemical Vapour Deposited Hard Coatings	155
S. Li, Y. Shi, X. Xu, H. Yang, C. Zhao; Qingdao, P.R. China	
Plasma Assisted CVD of TiN-like Coatings	163
F. H. M. Sanders, Eindhoven, NL	
TiC-Layers on Steel by Pulsed DC-Plasma CVD	171
K.-T. Rie, K. Detjen, S. Eisenberg, Braunschweig, FRG	
Formation of Titanium Nitride and Composite Layers under Glow Discharge Conditions	177
T. Wierzchoń, J. Michalski, T. Karpiński, Warsaw, Poland	
Examination of the Growth of a-Si:C:N:H-Films from a Hexamethyldisilazane-Plasma	185
K. W. Gerstenberg, Hamburg, FRG	
Overview on CVD and PVD Coated Carbide Metalcutting Tools	191
D. T. Quinto, Greensburg, USA	

Plasma Diffusion Treatment

Plasma Assisted Diffusion Treatment	201
K.-T. Rie Braunschweig, FRG	

Some Observations on Plasma Nitriding Austenitic Stainless Steel P. A. Dearnley, Cambridge; G. G. A. Hibberd, T. Bell, Birmingham, U.K. A. Namvar, Kashan, Iran	219
Plasma Nitriding with Air H.-J. Kölbel, Th. Lampe, G. Laudien, Wolfsburg, FRG	227
The Effect of Partial Nitrogen Pressure on the Formation of Nitride Layers on Steels J. Stanislav, V. Kubicek, P. Hubner, V. Prochazka, Prague, CSSR	233
Plasma Diffusion Treatment of Sintered Materials – An Austenitic Thermochemical Process K.-T. Rie, F. Schnatbaum, Braunschweig, FRG	241
Ion-Sulfo-Carbonitriding of Steel in the Vapor of Mixed Ammonia-Alcohol- Carbon Disulfide B. Q. Wang, Xian, P.R. China	251
Progress in the Control of Plasmanitriding and -carburizing for better Layer Consistency and Reproducibility B. Edenhofer, Kleve, FRG	257
Plasma Nitriding: Processes and Mechanisms A. Leyland, K. S. Fancey, A. Matthews, Hull; T. Bell, Birmingham, U.K. S. C. Kwon, M. J. Park, Changwon, S. Korea	269
Plasma(Ion)nitriding and Plasma(Ion)nitrocarburizing Its Units and its Applications F. Hombeck, W. Oppel, W. Rembges, Leverkusen, FRG	277
The Effects of Nitrogen on Surface Layer Structures of Plasma Complex-treated GCr15 Steel J. Sun, L. Yang, G. Feng, Dalian, P.R. China	289
The Research of a Complex Craft of Non-Etching Iron Plating- Ionitrocarburizing X. Hu, L. Yang, X. Ni, D. Yang, Dalian, P. R. China	295
The Study on the Feature of Plasma Carburizing G. Li, L. Yang, Dalian, P.R. China	299
A Study on Plasma Carburizing without Auxiliary Heater L. Yang, S. Liu, Dalian, P.R. China	305
Plasma Carburizing as an Alternative Process of Carburizing St. Eisenberg, K.-T. Rie, Braunschweig, FRG	311
Plasma Spraying	
The Deposition of Turbine Blade Coatings Using Low-Pressure, Multigun Plasma Spray Processing J. R. Raider, D. M. Gray, Schenectady, NY, USA	321

Effect of Coating Configuration and Heat Treatment on the Thermal Shock Resistant Properties of Ceramic Plasma Sprayed Coatings M. Fukumoto, N. Ueyama, I. Okane, Toyohashi, Japan	327
Influence of Porosity on the Properties of Plasma Sprayed Zirconia Coatings H.-D. Steffens, U. Fischer, Z. Babiak, Dortmund, FRG	335
On the Behaviour of Overlay Coatings in Stationary Gas Turbines B. Basler, W. Hoffelner, Baden, CH; R. Bürgel, Mannheim, FRG	347
Production and Application of Thick and Non-porous LPPS-Coatings of Nimonic 90 on Tools for the Production of Special-Type Glasses J. Disam, Mainz, FRG; A. Sickinger, Irvine CA, USA; V. Wilms, G. Johner, Hanau, FRG	355
The Microstructural Characterization of Plasma Sprayed and Physical Vapor Deposited Partially Stabilized Zirconia Thermal Barrier Coatings E. Y. Lee, R. R. Biederman, R. D. Sisson, Jr., Worcester, MA, USA	365
Design of a Computer-Controlled Vacuum Plasma Spray System for Production Applications H.-M. Höhle, W. Dietsch, Hattersheim FRG	373
Upgrading of Plasma Sprayed Coatings by Laser Treatment for Corrosion Resistance and by Hot Isostatic Pressing for Wear Resistance M. Hannotiau, J. Leunen, J. Sleurs, S. Heusdains, H. Tas, Mol, Belgium	387

Microelectronics, Electrical and Magnetical Layers

Plasma Diagnostics in Reactive Low Pressure Discharges K. Wiesemann, Bochum, FRG	397
Influence of RF-Diode, RF-Magnetron and DC-Magnetron Mode on the Crystallographic and Magnetic Properties of Sputtered Co-Cr Films A. Werner, H. Hibst, E. Hädicke, Ludwigshafen, FRG	415
In Situ Magneto-Optically Controlled Thin Film Growth D. Weller, W. Reim, Erlangen, FRG K. Balasubramanian, Tucson, Arizona, USA	423
Electrical Tests of LPCVD Tungsten Layers for VLSI Metallization M. Pospisil, F. Slaby, J. Gurovic, Prague, CSSR	431
Preparation of PECVD-Silicon-Nitride and PECVD-Silicon-Oxide Layers for Semiconductor Production in an ASM Horizontal-Tube-System K. Möhring, Hamburg, FRG	435

Preparation of YBaCuO Films by d.c.Magnetron Sputtering W. Shi, J. Sun, L. Liu, Zh. Qi, Hefei, P.R. China	443
Silicon Dioxide Deposition by Use of Microwave Plasma M. Oda, Y. Kinoshita, T. Kobayashi, Hyogo, Japan	451
Etching	
Characteristics of Etching $Ga_xAl_yIn_{1-x-y}As$ by RIE and CARIBE A. P. Webb, P. V. Dennis, Caswell, Towcester, U.K.	459
High Flux Plasma Etching at Low Ion Energies A. D. Kuypers, H. J. Hopman, Amsterdam, NL	465
Inhibitor Films as Microetching Tools in Pattern Transfer Technology I. W. Rangelow, R. Kassing, Kassel, FRG	473
Fence-like Residue Formation during Aluminum Dry Etching I. Daraktchiev, F. Cassiers, D. Goossens, St-Niklaas, Belgium	479
Modification of SiO_2 Surface with Electron, Ion Beam and Plasma J. Han, P. Wang, Z. Jin, F. Chen, M. Chen, Beijing, P.R. China	491
Multistep RIE of Aluminium and its Alloys I. Hussla, P. Baumann, G. Castrischer, H. Grünwald, G. Lorenz, H. Ramisch, Alzenau, FRG; P. Banks, Oxford, U.K.	495
Computer On-line Reflectometry for End-point Detection and System Control of Plasma-Induced Etching and Deposition G. Lorenz, K. Enke, I. Hussla, T.-M. Pang, C. Schmitt, Alzenau, FRG P. Banks, Oxford, U.K.	503
Planarization of Oxide Films in Double Metal Technologies by Using a Resist Etch Back Technique J. Frick, K. Pfeifer, Hamburg, FRG	511
Physical Vapor Deposition	
Plasma Assisted PVD Coating Technologies, Industrial Practice E. Bergmann, E. Moll, Balzers, Liechtenstein	521
An Investigation on Plasma Assisted Plating System for Thin Film Engineering Z. B. Hui, W. Y. Ding, Shanghai, P.R. China	529
Investigation of Plasma Deposited (Ti,Al)N Coating on Aluminium Alloys Z. Gu, C. Jiang, L. Yang, Dalian, P.R. China	535
Ion Bombardment Effects on (Ti,Al)N Deposits by Biased Activated Reactive Evaporation B. H. Hahn, J. H. Jun, J. E. Lim, Seoul, Korea	541

Alternative Nitride Coatings by Cathodic Arc Evaporation H. Randhawa, Boulder, CO, USA; H. M. Gabriel, Weiterstadt, FRG	547
Steered Arc Technology E. Ertürk, H.-J. Heuvel, H.-G. Dederichs, Bergisch Gladbach, FRG	553
Preparation and Application of Thin Films on Flexible Substrates W. Müller, V. Fronz, V. Neveling, W. Siefert, Freiburg, FRG	561
Study of Plasma Nitro-Carbo-Titanizing of Steel and Cast Iron Surfaces L. Yang, D. Yang, Y. Li, Dalian, P.R. China	569

Sputtering

Development of New Wear-Resistant Low-Temperature Coatings by Magnetron Sputtering O. Knotek, M. Atzor, F. Jungblut, Aachen, FRG	579
Titanium Nitride Thin Films Deposited by Reactive Magnetron Sputtering G. P. Georgiev, D. N. Popov, Rousse, Bulgaria	587
Production and Optimization of Hard Coatings of Tungstene Carbide with Cobalt A. Cavaleiro, M. T. Vieira, C. S. Furtado, Coimbra, Portugal; G. Lempérière, J. M. Poitevin, Nantes, France	595
Decorative Coatings by PVD H. Erhart, S. Bastian, H. Petersen, Wilster, FRG	603
High Temperature Electrical Insulating Properties of RF Magnetron Sputtered Alumina Coatings on Copper P. Vuoristo, T. Mäntylä, P. Kettunen, Tampere, Finland	609
Influence of Target Properties on Sputtering Process and Thin Films for Magneto optics L. A. Berchtold, St. U. Schittny, W. Böhm, E. Schultheiß, P. Wirz, Hanau, FRG	617
Effect of Target Structure on the Magnetic Properties of MO Films Produced in a Large Scale Sputtering System E. Schultheiß, G. Bräuer, P. Wirz, St. U. Schittny, L. A. Berchtold, Hanau, FRG	625
The Etching Effect on Ti Target during d.c.Magnetron Sputtering W. Yao, Sh. Tung, W. Shi, Zh. Qi, Hefei, P.R. China	633
Model Attachement for Hard-Coating of Tools by Magnetron High-Rate Sputtering W. Precht, K. Reszka, W. Telinski, Koszalin, Poland	637

Structure and Properties of Magnetron-Sputtered Hard Coatings in the Ti-Zr-N System O. Knotek, M. Atzor, Aachen, FRG	643
Powder Target Process for Sputtering High Tc Superconducting Films W. G. Luo, A. L. Ding, Y. H. Huang, H. R. Zhuang, Shanghai, P.R. China	649
Some Features of Triode Magnetron Sputtering Q. X. Shen, L. F. Wang, Z. Y. Liu, Baotou, P.R. China	655
Comparison of Reactive Deposition of TiN _x Films by Magnetron Sputtering and Arc Evaporation J. Vyskočil, J. Musil, S. Kadlec, Prague, CSSR; W.-D. Münz, Hanau, FRG	661